

Title (en)

A HIGH SHRINKAGE SIDE BY SIDE TYPE COMPOSITE FILAMENT AND A METHOD FOR MANUFACTURING THE SAME

Title (de)

HOCHSCHRUMPFENDESVERBUNDFILAMENT DES TYPUS SEITE AN SEITE SOWIE SEINE HERSTELLUNG

Title (fr)

FILAMENT COMPOSE DE TYPE COTE-A-COTE A RETRAIT ELEVE ET SON PROCEDE DE FABRICATION

Publication

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Application

EP 03774281 A 20031121

Priority

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Abstract (en)

[origin: WO2004048650A1] The present invention relates to a high shrinkage side-by-side type composite filament, wherein two kinds of thermoplastic polymers are arranged side by side type and a boiling water shrinkage (Sr2) measured by the method (initial load = notified denier x 1/10g, static load = notified denier x 20/10g) of clause 5.10 of JIS L 1090 is 20 to 75% of a boiling water shrinkage (Sr1) measured by the method (initial load = notified denier x 1/30g, static load = notified denier x 40/30g) of clause 7.15 of JIS L 1013. The side-by-side type composite filament is made of two kinds of thermoplastic polymers having a number average molecular weight difference (iMn) of 5,000 to 15,000 upon spinning and the composite filament is drawn and heat-treated so as to satisfy the following physical properties: Temperature area exhibiting 95% of maximum thermal stress (Tmax, 95%): 120 to 230 °C Range of maximum thermal stress per denier : 0.1 to 0.4g/denier

IPC 1-7

D01D 5/30

IPC 8 full level

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CPC (source: EP KR US)

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- See references of WO 2004048650A1

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